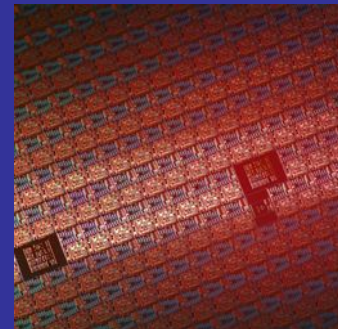




Accelerating the next technology revolution

# Fiducial Mark for Defect Mitigation Technology

Sean Huh, David Chan, George Huang  
(SEMATECH)  
P.Y Yang, Long He (Intel)  
Hakseung Han (Samsung)



# Executive Summary



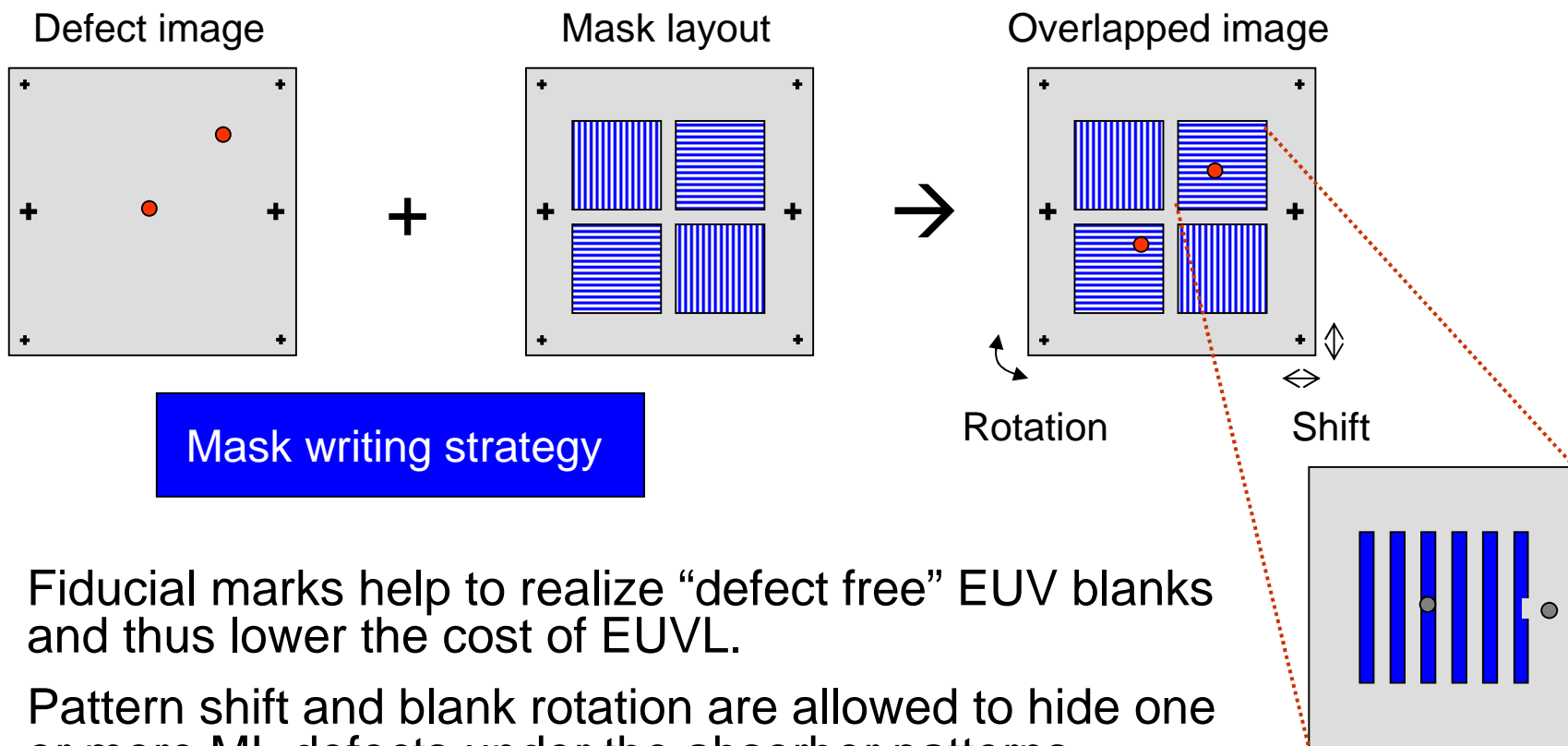
- **Objective and approach:**
  - Fiducial mark as defect mitigation strategy to “salvage” EUV blanks with a few defects to save cost and availability.
  - Use current tool infrastructures to reduce cost of implementation.
- **What are included in SEMI Standardization:**
  - Mark locations & Mark design
  - Mark readability including blank inspection tools, ebeam writers, and defect review tools.
- **What are NOT included:**
  - Methods to make marks
  - Mark depth, as long as meeting readability requirement.
- **Taskforce Members:** Intel, Samsung, GF, UMC, KLA, Lasertec, AGC, ASML, NuFlare, SEMATECH
- **Taskforce Key Deliverables and Schedule:** SEMI blue ballot – Q4, 09, Yellow ballot – Q1, 10.

# The Requirement of Fiducial Mark



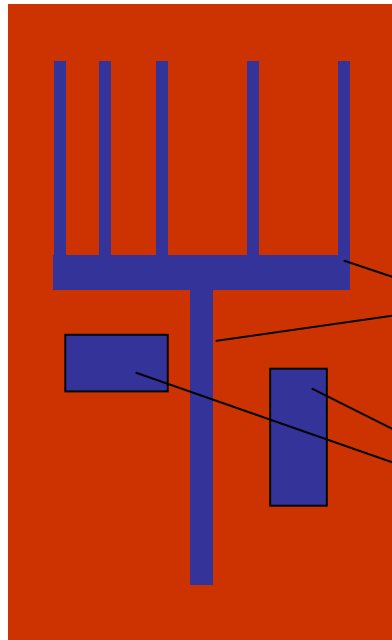
- Reserved area for fiducial mark on the blankmask
  - Fiducial marks should be rotationally symmetric to allow blank rotation (90 or 180 degree rotations only).
  - The region should not be used by other tools.
- Mark contrast
  - The mark should be readable and usable for alignment by blank inspection and ebeam writing tool.
- The dimension of fiducial mark
  - The mark size and fidelity should provide accurate position signal.

# How to Use Defect Information?



- Fiducial marks help to realize “defect free” EUV blanks and thus lower the cost of EUVL.
- Pattern shift and blank rotation are allowed to hide one or more ML defects under the absorber patterns.
- ML defects that are completely under the absorber will not print on the wafer.

# Defect Mitigation Technology using Fiducial Mark



Zone 1 : Critical smallest CD

Zone 2 : Less critical large CD

Zone 3 : Large dummy or pad, CD is not important

Mask Layout

➤ Zone2 or 3 will be first sort for fiducial mark application

# SEMI Fiducial Mark Draft Ballot



## **SEMI DOCUMENT XXXX- DRAFT- October 6, 2009 SPECIFICATION OF FIDUCIAL MARKS FOR EUVL MASK BLANKS**

### **1 Purpose**

This standard specifies key requirements of mask fiducial marks that can be used as a coordinate system for referencing defect locations on EUV blanks.

### **2 Scope**

2.1 This standard is intended to set an appropriate level of technical specifications of mask fiducial marks, such as their locations, shapes, sizes, line dimensions, limits of variation, and readability by mask metrology and pattern write tools.

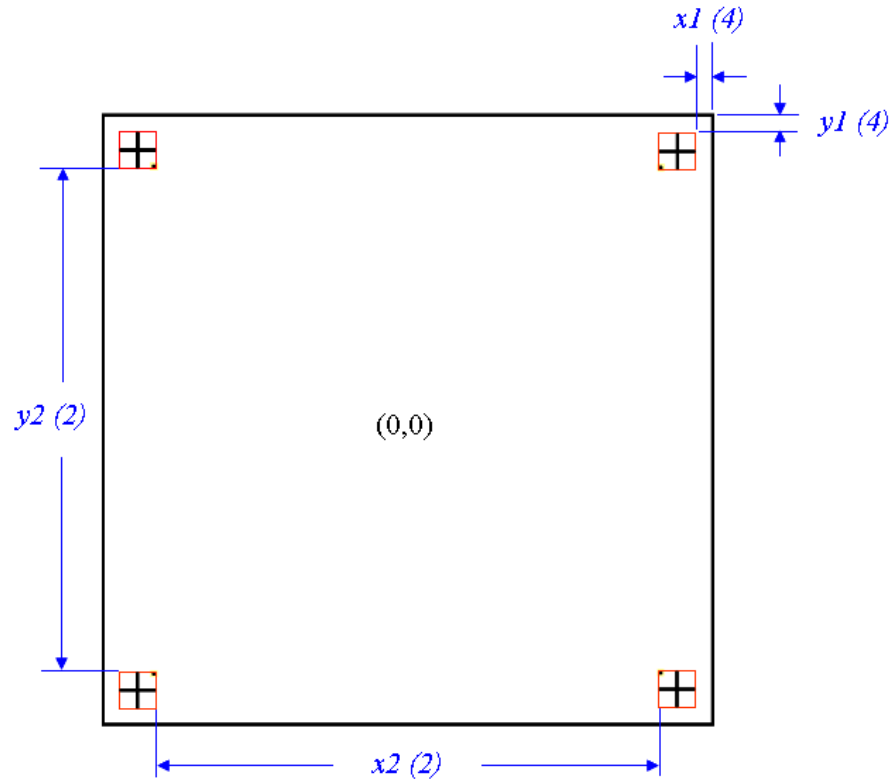
2.2 To allow innovation, this standard does not specify techniques to be used, or how the fiducial marks are generated.

**NOTICE:** This standard does not purport to address safety issues, if any, associated with its use. It is the responsibility of the users of this standard to establish appropriate safety and health practices and determine the applicability of regulatory or other limitations prior to use.

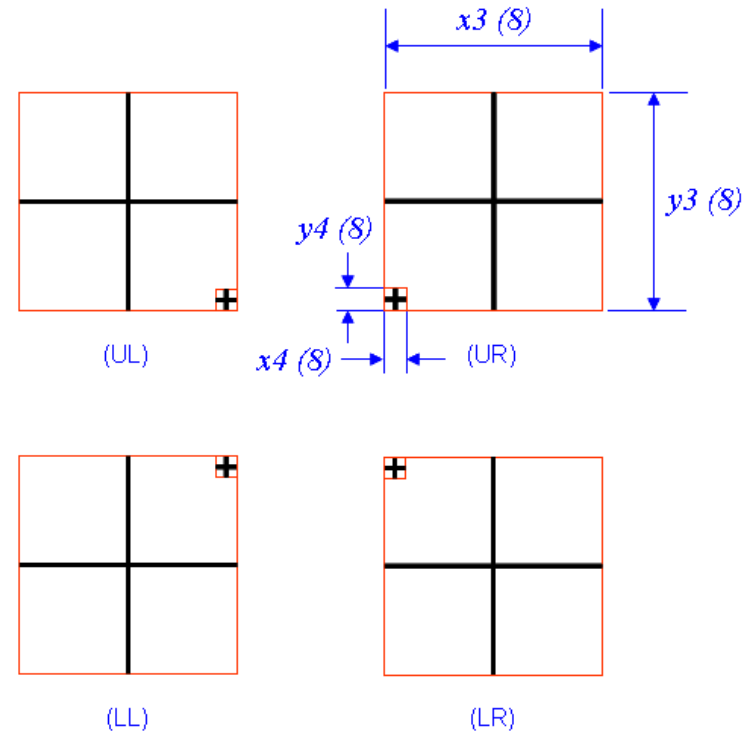
### **3 Referenced Standards and Documents**

3.1 *SEMI Standards*

# Fiducial Mark Layout (Draft)



Fiducial mark layout on an EUV mask blank (not to scale). One mark is placed at each corner.



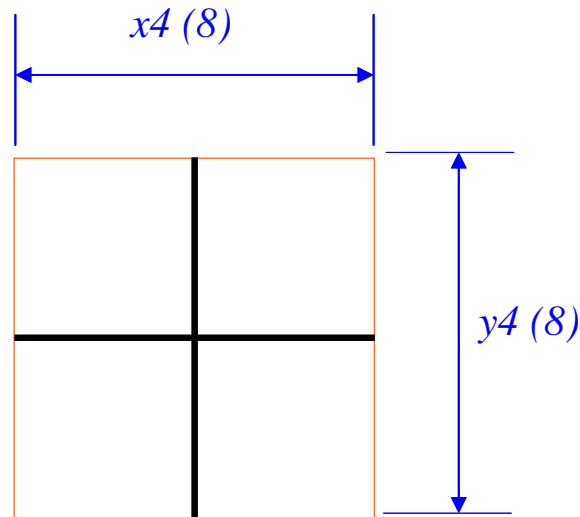
Layout of coarse and fine marks for all the four fiducial marks (not to scale). (Red lines are guide to eyes)

# Draft FM Specifications



Symbol Used	Figure	Value (mm unless specified)	Tolerance (mm unless specified)	Reference Measured From	Feature Measured To
x1	1	5.0	Minimal	Nearest edge of mask blank	Outmost line end of coarse mark
x2	1	135.000	±0.010	Inmost line ends of the fine and/or coarse marks on the left	Inmost line ends of the fine and/or coarse marks on the right
x3	2	3.000	±0.010	Left end of coarse mark	Right end of coarse mark
x4	2	0.100	±0.010	Left end of fine mark	Right end of fine mark
y1	1	5.0	Minimal	Nearest edge of mask blank	Outmost line end of coarse mark
y2	1	135.000	±0.010	Inmost line ends of the fine and/or coarse marks on the bottom	Inmost line ends of the fine and/or coarse marks on the top
y3	2	3.000	±0.010	Left end of coarse mark	Right end of coarse mark
y4	2	0.100	±0.010	Lower end of fine mark	Upper end of fine mark
CD (for both coarse and fine marks)		4.0 um	0.1 um	CD is defined as line width of both the fine and coarse marks.	
LER (3σ on each side)		10.0 nm	Maximal	3σ on each side	

## Other Fiducial Mark Design Options: #1



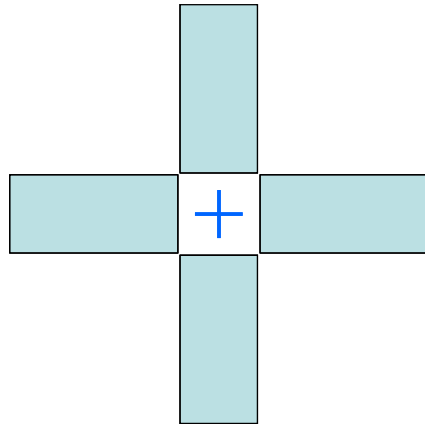
Suggested by E-beam writing supplier. Overall, it may be the best option.

**Option #1.** Increase the line length of coarse mark ( $x4/y4$ ) to 4mm (from 3), and eliminate fine marks. (Red lines are guide to eyes)

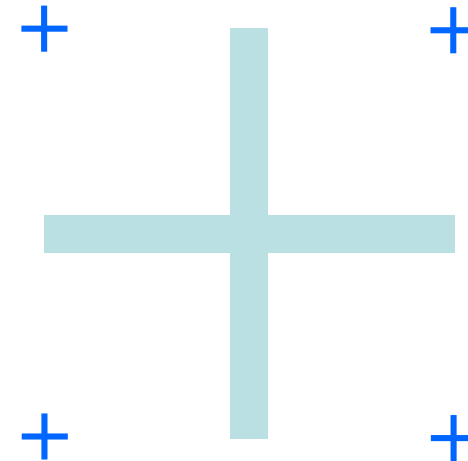
**The good: Simplicity. Symmetric**

**The Bad: The maximum central area ( $x2/y2$ ) would be reduced to ~133nm (from ~135mm).**

## Other Fiducial Mark Design Options: #2, #3



**Option #2.** Aligned up fine and course marks to they are centered at the same location.



**Option #3.** Place one fine mark at each corner of the coarse mark.

**The good:** All the four fiducial marks (coarse + fine) will be identical/and symmetric.

**The Bad:** Complex.

# Defect Coverage Accuracy



<b>DRAM Half pitch</b>	<b>11</b>	<b>16</b>	<b>23</b>	<b>32</b>	<b>45</b>	<b>65</b>	<b>90</b>	<b>130</b>
Mask CD (4x)	44	64	92	128	180	260	360	520
Mask uniformity (3 sigma)	1.3	1.8	2.6	3.7	5.2	7.3	10.2	14.7
Mask MTT (+/- Range)	0.9	1.3	1.8	2.6	3.6	5.2	7.2	10.4
Inspection tool sensitivity	25	25	25	25	25	25	25	25
E-beam alignment accuracy to fiducial mark	25	25	25	25	25	25	25	25
E-beam stage accuracy (sigma)	3.3	3.3	3.3	3.3	3.3	3.3	3.3	3.3
Max space for defect to move considering mask error	34.7	50.6	72.7	101.0	142.1	205.4	284.5	410.9
Max space for defect to move without considering mask error	44	64	92	128	180	260	360	520

Required inspection tool accuracy (3sigma)								
<i>with mask error</i>	-	<b>17.5</b>	<b>49.1</b>	<b>82.3</b>	<b>128.1</b>	<b>197.6</b>	<b>283.4</b>	<b>420.4</b>
<i>without mask error</i>	-	<b>22.5</b>	<b>54.0</b>	<b>88.7</b>	<b>136.9</b>	<b>209.8</b>	<b>300.3</b>	<b>444.7</b>

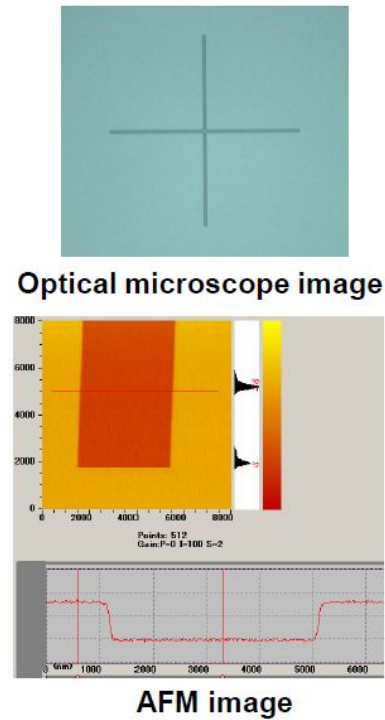
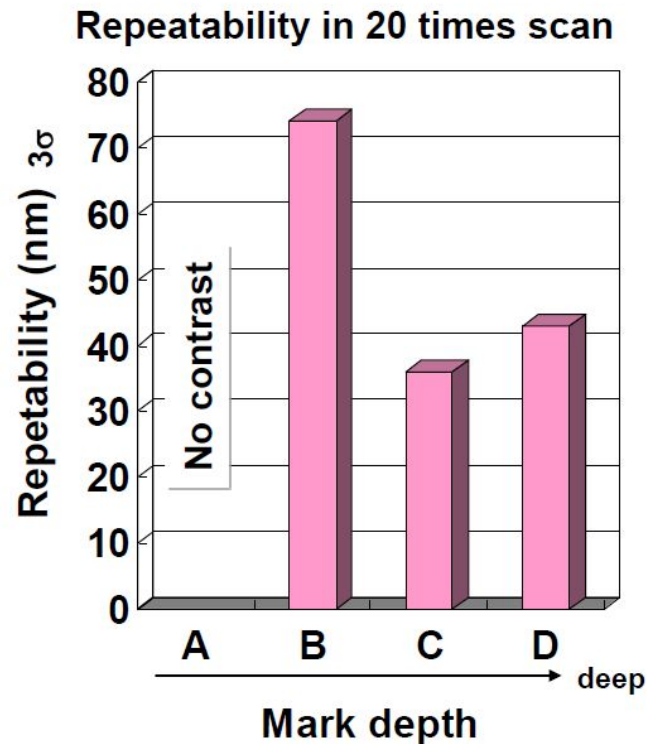
$$\sigma^2(A) = \sigma^2(B) + \sigma^2(C) + \sigma^2(D)$$

- A : Max space for defect to move under absorber
- B : Defect location measurement error (include both stage accuracy and repeatability)
- C : Ebeam alignment accuracy to fiducial mark
- D : Ebeam stage accuracy

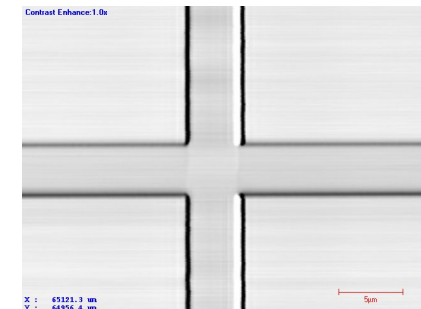
# Demonstration of Fiducial Mark by Blank Company



## Initial results in EB scan



Intel Lasertec M1350 image of ML fiducial mark

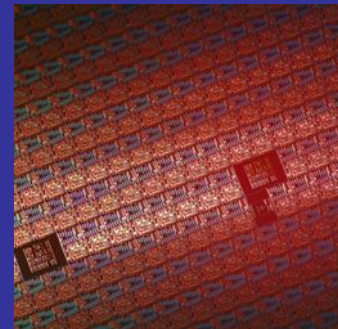


- ◆ Optimum depth for mark was decided from actual EB scan evaluation
- ◆ Repeatability would be improved by optimization of EB writing process

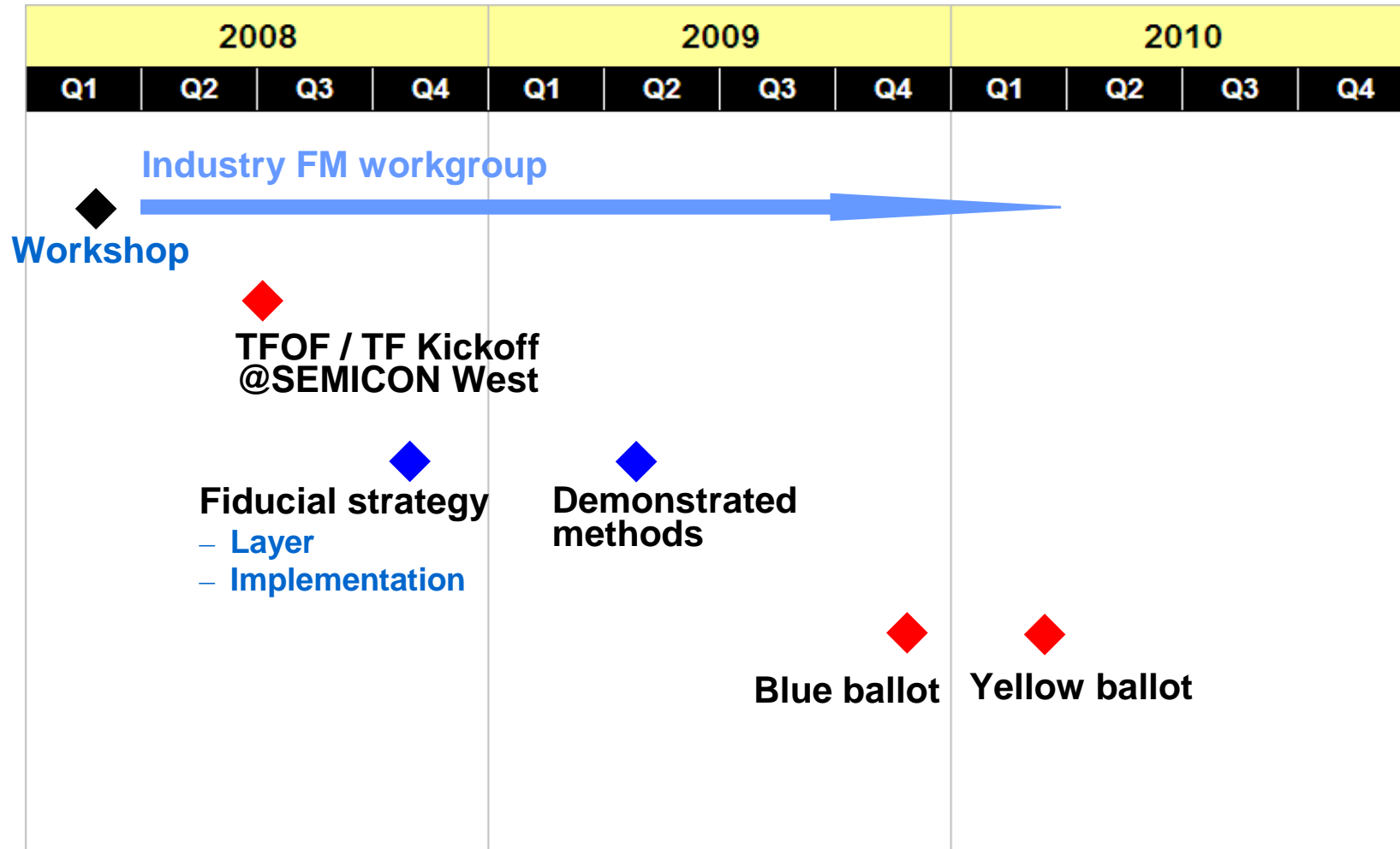


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# Backup



# Proposed Roadmap for Fiducial Mark Standardization



# Tentative Plan



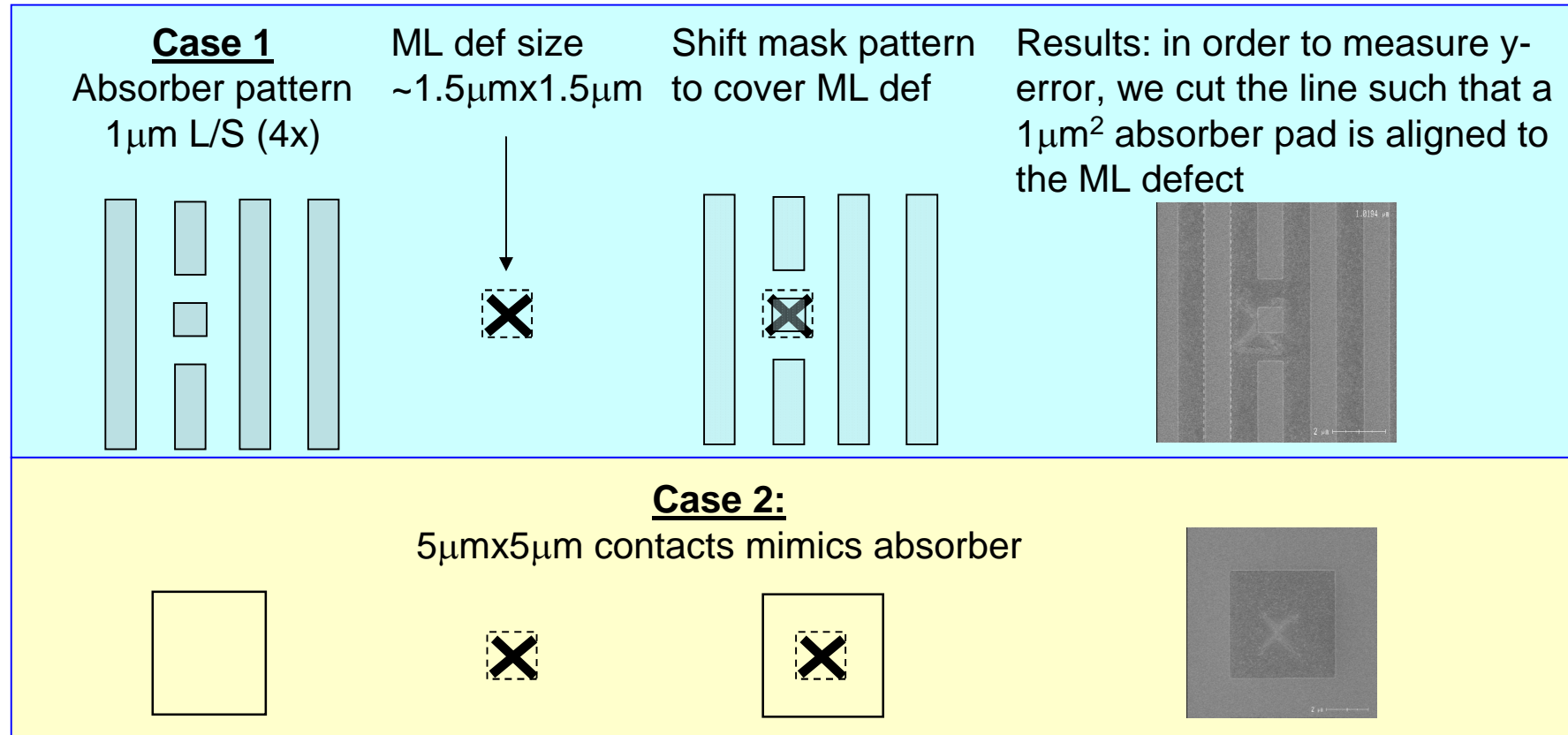
- Request to SEMI NA Micro Patterning Committee in its 2/28/09 (2010?) meeting, for Cycle 6 yellow (Blue?) ballot voting (9/14-10/14/09).
- Draft blue ballot review by TF, at SEMICON West (July, 2009)
- Yellow (Blue?) ballot submission on 8/31/09
- In the meantime, develop/demonstrate marking methods.

# The Purpose of Fiducial Mark



- Fiducial marks are mainly for ML defect mitigation technology which allows to utilize a mask blank with limited defects.
- Implementation of ML defect mitigation scheme can reduce blank cost by increasing blank yield.

# Example of ML Defect Coverage via Absorber Pattern

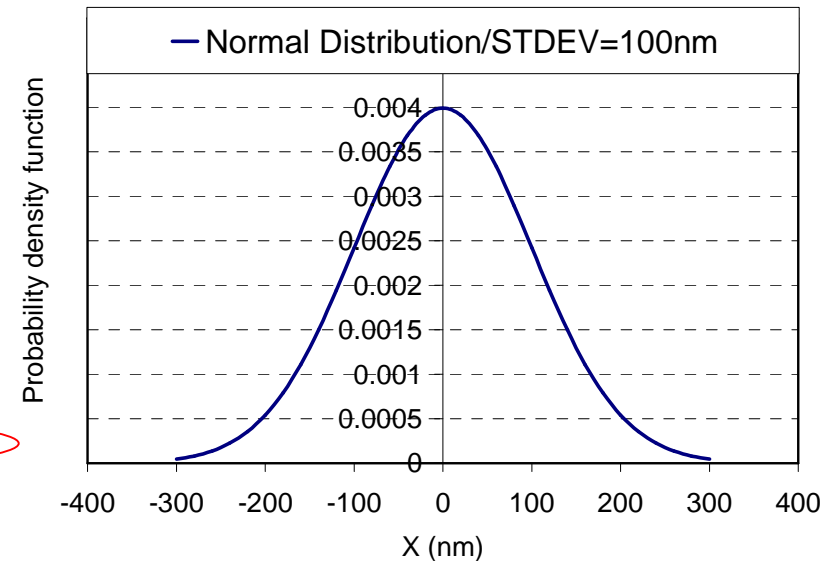


- The experiment used ML indentation as the first set fiducial mark and first layer e-beam patterned fiducial mark as the final fiducial mark.

# Small Defect Position and Alignment Error Allows Small Absorber Area



For defect coverage position Normal Distribution with standard deviation $\sigma$ (A)	
Absorber pad (square) size	Probability of covering a defect when its average position is at the pad center
Defect size+ $1\sigma$ (A)	38%
Defect size+ $2\sigma$ (A)	68%
Defect size+ $4\sigma$ (A)	95%
Defect size+ $6\sigma$ (A)	99.7%



$$\sigma^2(A) = \sigma^2(B) + \sigma^2(C) + \sigma^2(D)$$

- Reducing  $\sigma(B)$ ,  $\sigma(C)$ , and  $\sigma(D)$  will allow the use of small absorber pad

# Fiducial Mark TF activity/plan



- **The core team meets on as-needed base, currently focusing on ballot editing.**
  - Next meeting slated for 10/?? Everyone is welcome to attend.
- **Targeted to submit informational (Blue) ballot in November, 2009.**
- **Targeted to submit Letter (Yellow) ballot in March 2010.**
- **Final standard approval targeted for Summer 2010.**